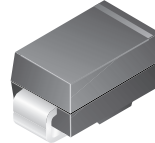


RGF1A - RGF1M

Features

- Glass passivated junction.
- For surface mounted application.
- Low forward voltage drop.
- High current capability.
- Easy pick and place.
- High surge current capability.



SMA/DO-214AC
 COLOR BAND DENOTES CATHODE

1.0 Ampere Fast Recovery Rectifiers

Absolute Maximum Ratings*

$T_A = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Value | Units |
|-----------------|--|--------------|---------------------------|
| $I_{F(AV)}$ | Average Rectified Current @ $T_L = 125^\circ\text{C}$ | 1.0 | A |
| I_{FSM} | Non-repetitive Peak Forward Surge Current 8.3 ms single half-sine-wave Superimposed on rated load (JEDEC method) | 30 | A |
| P_D | Total Device Dissipation Derate above 25°C | 1.76 11.7 | W mW/ $^\circ\text{C}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient ** | 85 | $^\circ\text{C/W}$ |
| $R_{\theta JL}$ | Thermal Resistance, Junction to Lead** | 28 | $^\circ\text{C/W}$ |
| T_{stg} | Storage Temperature Range | -65 to +175 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature | -65 to +175 | $^\circ\text{C}$ |

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

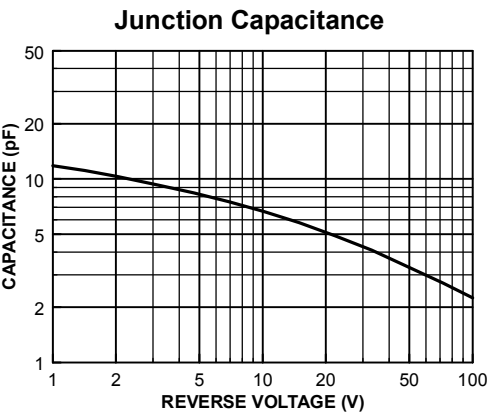
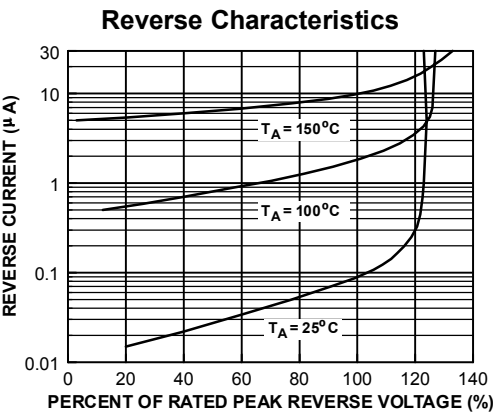
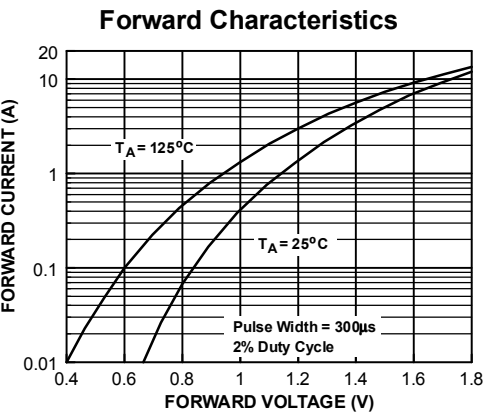
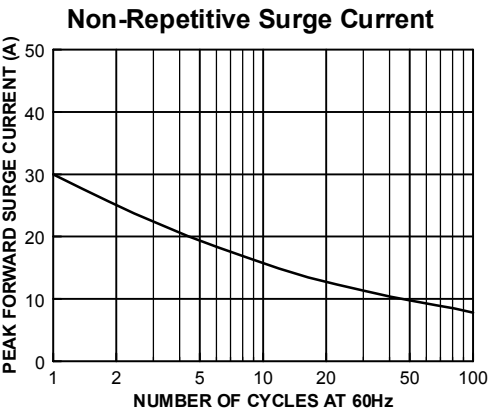
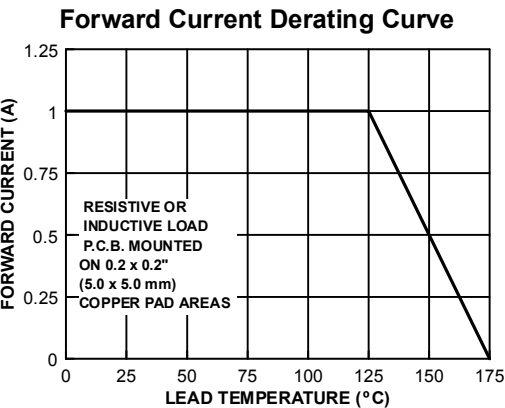
**Device mounted on FR-4 PCB 0.013 mm.

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Device | | | | | | | Units |
|------------------|---|------------|-----|-----|-----|-----|-----|------|----------|
| | | 1A | 1B | 1D | 1G | 1J | 1K | 1M | |
| V _{RRM} | Maximum Repetitive Reverse Voltage | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| V _{RMS} | Maximum RMS Voltage | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| V _R | DC Reverse Voltage (Rated V _R) | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| I _R | Maximum Instantaneous Reverse Current @ rated V _R T _A = 25°C T _A = 125°C | 5.0 100 | | | | | | | μA μA |
| V _{FM} | Maximum Instantaneous Forward Voltage @ 1.0 A | 1.3 | | | | | | | V |
| t _{rr} | Maximum Reverse Recovery Time I _F = 0.5 A, I _R = 1.0 A, I _{rr} = 0.25 A | 150 | | | | 250 | 500 | | ns |
| C | Typical Junction Capacitance V _R = 4.0 V, f = 1.0 MHz | 8.5 | | | | | | | pF |

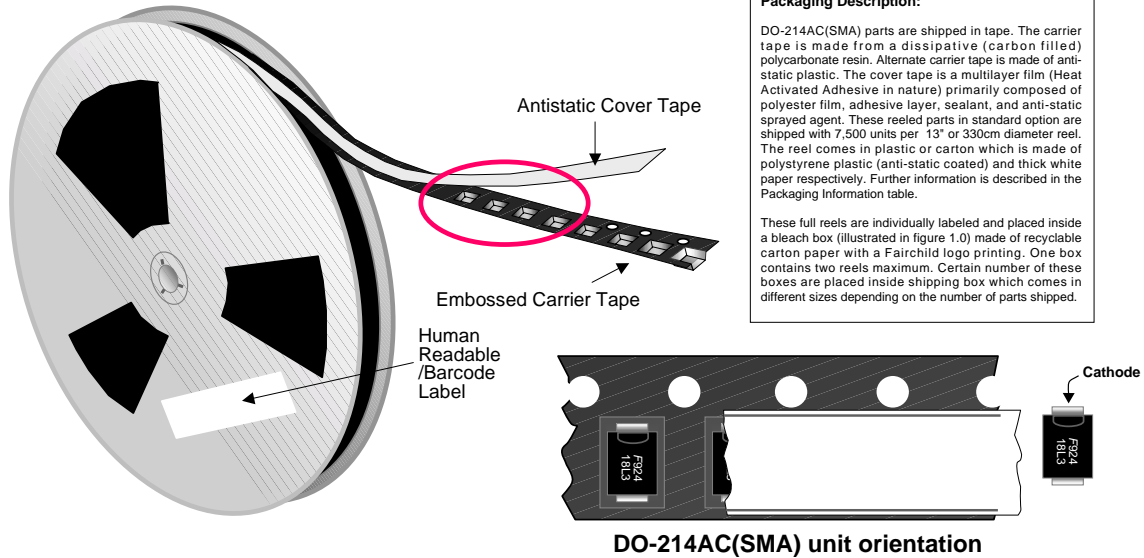
Typical Characteristics



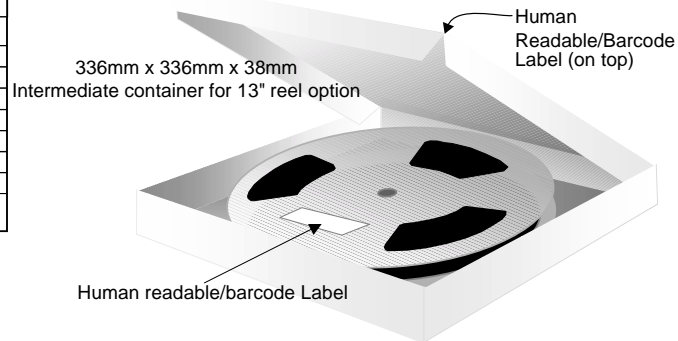
DO-214AC(SMA) Tape and Reel Data

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DO-214AC(SMA) Packaging Configuration: Figure 1.0



| DO-214AC(SMA) Packaging Information | | |
|-------------------------------------|------------------------------|------------------------------|
| Packaging Option | Under package code P5 | Under package code MA |
| Packaging type | TNR | TNR |
| Qty per Reel/Tube/Bag | 7,500 | 5,000 |
| Reel Size (inch diameter) | 13 | 13 |
| Box Dimension (mm) | 336X336X38 | 340X350X340 |
| Max qty per Box | 15,000 | 10,000 |
| Weight per unit (gm) | 0.064 | 0.064 |
| Weight per Reel (kg) | 0.860 | 0.750 |
| Note/Comments | Human readable label | Barcode label |



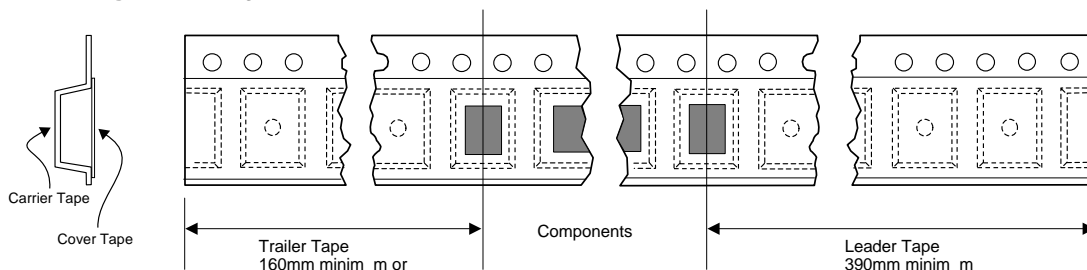
Human Readable Label sample



F63TNR Label sample



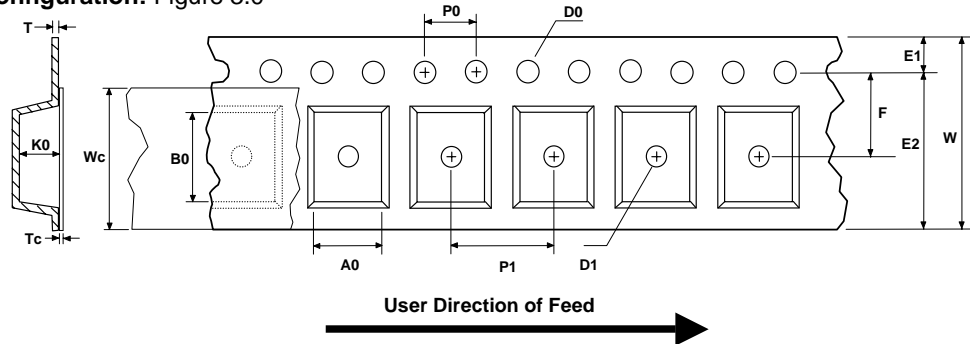
DO-214AC(SMA) Tape Leader and Trailer Configuration: Figure 2.0



DO-214AC(SMA) Tape and Reel Data, continued

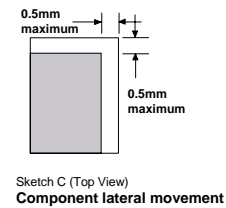
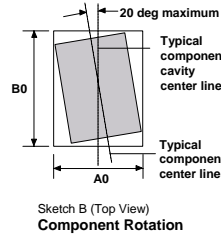
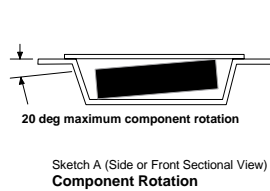
DO-214AC(SMA) Embossed Carrier Tape

Configuration: Figure 3.0



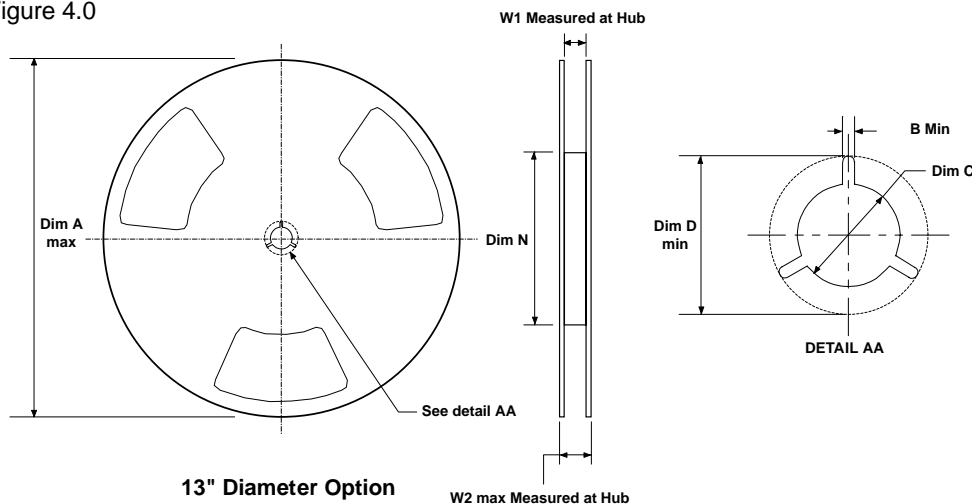
| Dimensions are in millimeter | | | | | | | | | | | | | | |
|------------------------------|-----------------|-----------------|----------------|-----------------|-------------------|-----------------|--------------|----------------|---------------|---------------|-----------------|-----------------|-----------------|-----------------|
| Pkg type | A0 | B0 | W | D0 | D1 | E1 | E2 | F | P1 | P0 | K0 | T | Wc | Tc |
| DO-214AC(SMA) (12mm) | 2.72 +/-0.10 | 5.25 +/-0.10 | 12.0 +/-0.3 | 1.55 +/-0.05 | 1.125 +/-0.125 | 1.75 +/-0.10 | 10.25 min | 5.5 +/-0.05 | 4.0 +/-0.1 | 4.0 +/-0.1 | 2.45 +/-0.10 | 0.23 +/-0.10 | 9.3 +/-0.025 | 0.06 +/-0.02 |

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



DO-214AC(SMA) Reel Configuration:

Figure 4.0

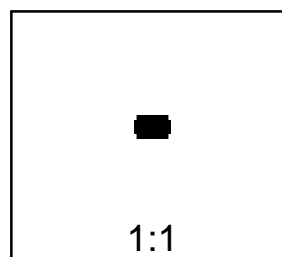
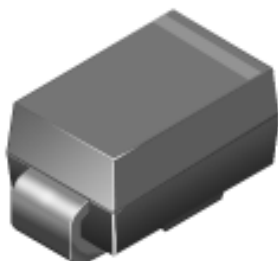


| Dimensions are in inches and millimeters | | | | | | | | |
|--|-------------|-------------|--------------|-----------------------------------|---------------|----------------|-----------------------------------|---------------|
| Tape Size | Reel Option | Dim A | Dim B | Dim C | Dim D | Dim N | Dim W1 | Dim W2 |
| 12mm | 13" Dia | 13.0 330 | 0.059 1.5 | 512 +0.020/-0.008 13 +0.5/-0.2 | 0.795 20.2 | 1.97 50 min | 0.331 +0.059/-0.000 8.4 +1.5/0 | 0.567 14.4 |

DO-214AC(SMA) Package Dimensions



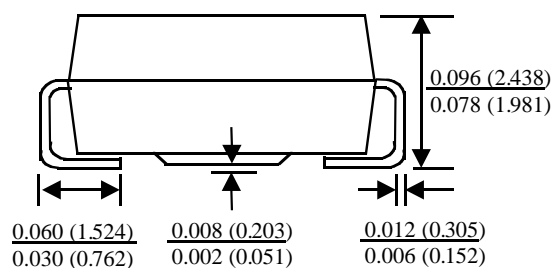
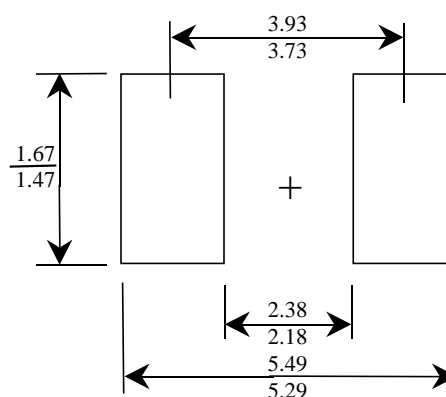
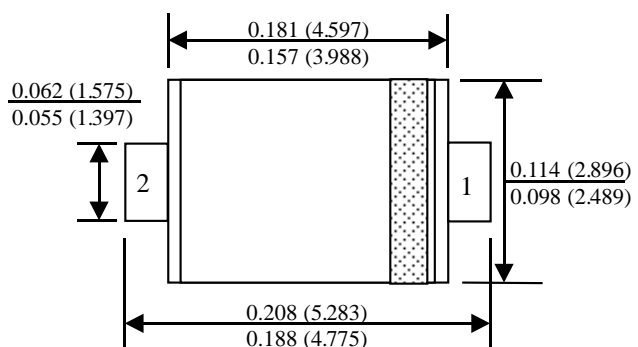
DO-214AC(SMA) (FS PKG Code P5)



Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.064



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